Model JFP PP5-6 SERIES

FLIP CHIP DIE BONDER

APPLICATIONS:
Pick & Place
Flip Chip assembly
Very small and large component
MEMS, MMICS, IR sensor, opto, laser diode...
Thermo-sonic die bonding
Reflow, thermal cycle
Eutectic thermo cycle
Wafer sorter up to 8”
Dispenser for epoxy & solder paste
Stamping

The JFP PP5 is most versatile semi automatic Flip-Chip platform. It can be used in a wide field of applications such as; Standard IC; MMIC; MEMS; VECEL....
It achieves maximum accuracy placement using high quality optical device. Flip feature will allow a perfect alignment of parts and substrate, mixing both video pictures with a placement @$< 3 \mu m @ 3 sigma$.
The PP5 series provide customers with the best cost / performance system on the market
Our proven expertise in bonding application effectively provides the technology and support to help our customers. A robust, and reliable mechanical concept, designed to be external vibration free. The PP5 is user friendly, flexible and requires minimal training to operate.
Specifications

Model: Flip Chip Die Bonder PPS-6
- Pick & Place regular device
- Pick & Place flipped device

Motorized Tables: X 250mm, Y 100mm / 1µm
- Manual Theta
- Joystick control: 2 speeds, adjustable

Pick & Place Head
- Motorized Z
- Vacuum picking tool, 1/8
- Minimum force: 10gr

Die size:
- Minimum 200*200 µm
- Minimum 25mm*25mm

Substrate handled:
- Up to 300x500 mm

Flip chip:
- Up-looking camera
- Dual vision computing system

Vision:
- Dual CCD Color camera
- 17” TFT panel
- Up-looking camera
- Dual video mixer for simultaneous alignment
- Target Crosshair generator

Light:
- Direct and pen light, independent per camera

Ultrasonic Flip:
- High Power multi frequency digital ultrasonic generator

Transducer:
- Heavy duty 60Khz transducer

Alignment:
- Place Mode direct for flip application
- 2 Ref point / Indexed XY at P&P position

Parameters:
- Friendly Graphic user interface
- Force: 10gr to 6 Kgr programmable
- Bond Time: 1ms to 10sec programmable
- US Power: up to 30W programmable
- Scrub: XY amplitude and cycle programmable

Matrix:
- Mapping / step and repeat / 2 ref point / Indexed

Operating System: Windows XP PRO

Utilities:
- 100Vac to 230Vac / 500W
- Vacuum: 70%

Options
- Full inspection and customized criteria for sorting automation using vectorial recognition Cognex 8000.
- Eutectic Digital temperature profile control. 3 set points with nitrogen enclosure workholder
- Heated Work-Holder up to 8 inches (200mm)
- Double micro jet hot gaz
- Rework BGA & Flip chip with solder removal module
- Oven C4 compatible
- Heavy duty bond head, 3 ranges Programmable up to 15Kg
- Piezzo driven micro gripper pick up head
- Dispenser
- Stamping
- UV insulator

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